Surface Mount Schottky Power Rectifier

Plastic SOD-123 Package

This device uses the Schottky Barrier principle with a large area metal—to—silicon power diode. Ideally suited for low voltage, high frequency rectification or as free wheeling and polarity protection diodes in surface mount applications where compact size and weight are critical to the system. This package also provides an easy to work with alternative to leadless 34 package style.

Features

- · Guardring for Stress Protection
- Low Forward Voltage
- 125°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Package Designed for Optimal Automated Board Assembly
- ESD Ratings: Machine Model, C; Human Body Model, 3
- Pb-Free Packages are Available

Mechanical Characteristics

- Reel Options: MBR130T1 = 3,000 per 7 in reel/8 mm tape MBR130T3 = 10,000 per 13 in reel/8 mm tape
- Device Marking: S3
- Polarity Designator: Cathode Band
- Weight: 11.7 mg (approximately)
- Case: Epoxy, Molded
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 1.0 AMPERES 30 VOLTS



SOD-123 CASE 425 STYLE 1

MARKING DIAGRAM



S3 = Specific Device Code

M = Date Code

■ = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping [†]		
MBR130T1	SOD-123	3000/Tape & Reel		
MBR130T1G	SOD-123 (Pb-Free)	3000/Tape & Reel		
MBR130T3	SOD-123	10,000/Tape & Reel		
MBR130T3G	SOD-123 (Pb-Free)	10,000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	30	V
Average Rectified Forward Current (Rated V_R) $T_L = 65^{\circ}C$	I _{F(AV)}	1.0	А
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions, Halfwave, Single Phase, 60 Hz)	I _{FSM}	5.5	А
Storage Temperature Range	T _{stg}	-65 to +125	°C
Operating Junction Temperature	TJ	-65 to +125	°C
Voltage Rate of Change (Rated V _R)	dv/dt	1000	V/µs

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Ambient (Note 1)	$R_{\theta JA}$	230	°C/W
Thermal Resistance, Junction to Lead (Note 1)	$R_{\theta JL}$	108	°C/W

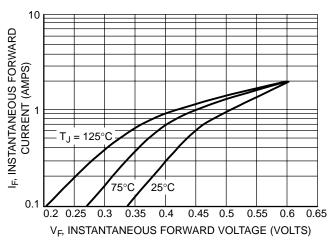
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 or FR-5 = 3.5 × 1.5 inches using a 1 inch Cu pad.

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Тур	Max	Unit
Maximum Instantaneous Forward Voltage (Note 2)	V _F			V
$(I_F = 0.1 \text{ A}, T_J = 25^{\circ}\text{C})$		_	0.35	
$(I_F = 0.7 \text{ A}, T_J = 25^{\circ}\text{C})$		_	0.45	
$(I_F = 1.0 \text{ A}, T_J = 25^{\circ}\text{C})$		0.47	_	
Maximum Instantaneous Reverse Current (Note 2)	I _R			μΑ
(Rated DC Voltage, T _C = 25°C)		6	0	
$(V_R = 5 \text{ V}, T_C = 25^{\circ}\text{C})$		1	0	

^{2.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2%.

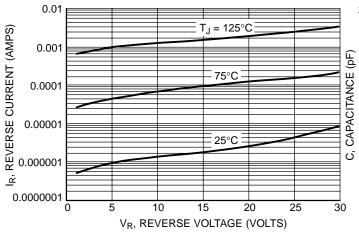


0.1 0.2 0.25 0.3 0.35 0.4 0.45 0.5 0.55 0.6 0.65

V_F, INSTANTANEOUS FORWARD VOLTAGE (VOLTS)

Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage



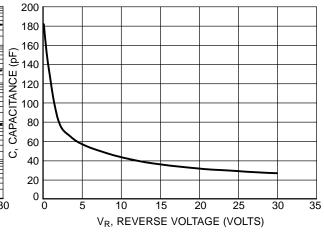
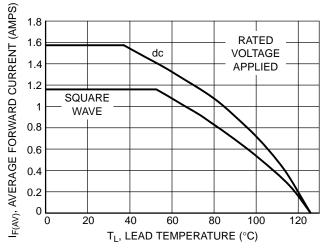


Figure 3. Typical Reverse Current

Figure 4. Typical Capacitance



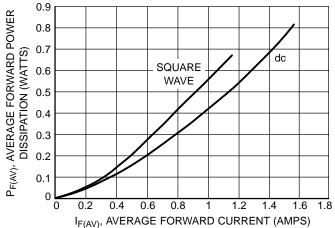
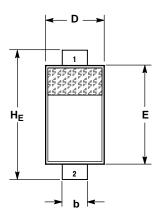


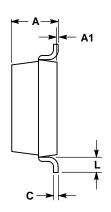
Figure 5. Current Derating, Lead, $R_{\theta JL} = 108^{\circ}C/W$

Figure 6. Forward Power Dissipation

PACKAGE DIMENSIONS

SOD-123 CASE 425-04 **ISSUE E**



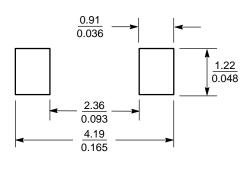


- 1. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.94	1.17	1.35	0.037	0.046	0.053
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.51	0.61	0.71	0.020	0.024	0.028
С			0.15		-	0.006
D	1.40	1.60	1.80	0.055	0.063	0.071
E	2.54	2.69	2.84	0.100	0.106	0.112
HE	3.56	3.68	3.86	0.140	0.145	0.152
L	0.25			0.010		

STYLE 1: PIN 1. CATHODE

SOLDERING FOOTPRINT*



mm inches SCALE 10:1

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and un are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082-1312 USA Phone: 480-829-7710 or 800-344-3860 Toll Free USA/Canada Fax: 480-829-7709 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free

Japan: ON Semiconductor, Japan Customer Focus Center 2-9-1 Kamimeguro, Meguro-ku, Tokyo, Japan 153-0051 Phone: 81-3-5773-3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative